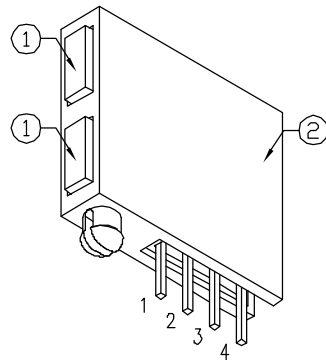
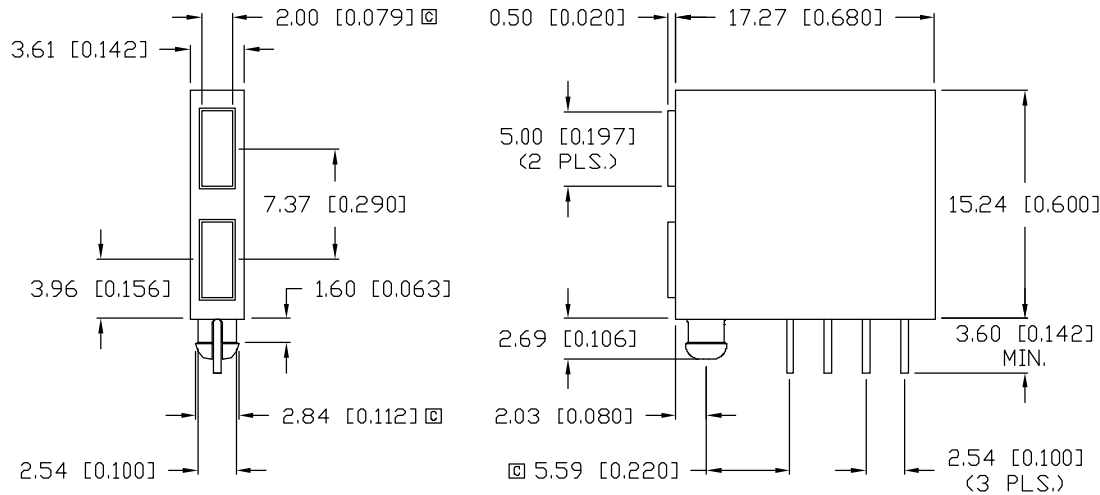


UNCONTROLLED DOCUMENT

PART NUMBER
SSF-LXH22573LGGD

REV.
D

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	UPDATED SAFE OPER SPECS.	9.12.95
B	E.C.N. #10336.	4.22.97
C	E.C.N. #10520.	6.8.99
D	E.C.N. #10BRDR. & REDRAWN.	5.10.01



LEADS:

1. GREEN ANODE.
2. GREEN CATHODE.
3. GREEN ANODE.
4. GREEN CATHODE.

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		565		nm	
FORWARD VOLTAGE		2.2	2.6	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_r=100\mu\text{A}$
AXIAL INTENSITY		10	0.6	mcd	$I_f=20\text{mA}$
			80	mcd	$I_f=2\text{mA}$
VIEWING ANGLE					2x theta
EMITTED COLOR:	GREEN				
EPOXY LENS FINISH:	GREEN DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C PER CHIP

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	25	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	$\text{mW}/^\circ\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^\circ\text{C}$
SOLDERING TEMP.	+260	$^\circ\text{C}$
2.0mm FROM BODY		3 SEC. MAX

* $t < 10\mu\text{s}$

NOTES:

1. SSL-LX2573LGD, GREEN LED (2 PCS.).
2. SSH-LXH22573 HOLDER, BLACK.

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*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN.= +DECIMAL PRECISION MAX.= +0.00 -DECIMAL PRECISION

REV. D PART NUMBER SSF-LXH22573LGGD

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2mm x 5mm PIGGYBACK RIGHT ANGLE INDICATOR,
LOW CURRENT SELECTION,
TWO 565nm GREEN LEDS, GREEN DIFFUSED LENS.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: CT	CHECKED BY:	APPROVED BY:	DATE: 7.13.93 PAGE: 1 OF 1 SCALE: N/A
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